



Modern Grinding Technology and Systems

Guest Editor:

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submissions:
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Message from the Guest Editor

Dear Colleagues,

This Special Issue will feature key innovations in the science and engineering of new grinding processes, abrasives, tools, machines, and systems for a range of important industrial topics. Topics will, not only feature well-known grinding processes and tools, but also innovations to solve new areas of application. Innovations may range from high-precision kinematics for grinding very large lenses and reflectors, through to medium-sized grinding machine processes, down to grinding very small components used in MEMS. Materials to be ground may include conventional engineering steels to aerospace materials, ceramics, and composites. Papers may also deal with novel topics, such as finishing of parts produced by 3D printing. Innovations may also include new features introduced into control systems to improve process efficiency or to integrate the grinding process more effectively into a wider manufacturing system. Papers will be considered that show significant improvements to any aspect of grinding processes, machines, materials, abrasives, wheel preparation, coolants, and lubricants.

Prof. Dr. W. Brian Rowe
Guest Editor





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